



## General Description

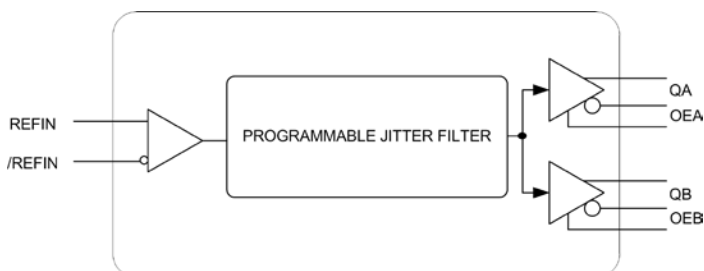
The PL904xxx series is a small form-factor, high performance, programmable device and a member of Micrel's JitterBlocker factory programmable jitter attenuators. The JitterBlocker product family cleans deterministic jitter by attenuating spurious components in the phase noise, thereby improving the phase jitter and the overall phase noise. The PL904xxx is capable of reducing multiple pico seconds of phase jitter in a clock to a level below  $0.5\text{ps}_{\text{RMS}}$  in most cases, making that clock usable for many more applications.

The PL904xxx operates on a single 2.5V or 3.3V supply and is housed in a small QFN package for a broad range of applications.

Input clock frequencies up to 250MHz can be filtered and frequency translation allows for output clock frequencies up to 850MHz. The input clock can be single-ended or differential.

Datasheets and support documentation are available on Micrel's web site at: [www.micrel.com](http://www.micrel.com).

## Block Diagram



## Features

- Input frequency up to 250MHz
- Output frequency up to 850MHz
- Programmable input type, differential or single-ended
- Up to two outputs with LVPECL, LVDS, HCSL, or LVCMOS logic types
- Output enable control for each output
- Jitter attenuation of 20db at 3MHz spur frequency
- Cleans up spurs to below  $0.5\text{ps}_{\text{RMS}}$  phase jitter
- Operating temperature range from  $-40^{\circ}\text{C}$  to  $85^{\circ}\text{C}$
- Available in 32-pin QFN GREEN/RoHS-compliant package
- Related devices:
  - PL902: LVCMOS, Period Jitter cleaning
  - PL903: Single ended input, one differential output, Phase Noise cleaning

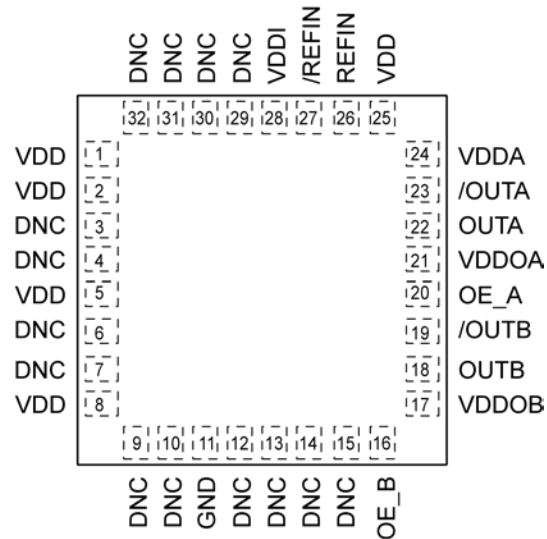
## Applications

- 1/10/40/100 Gigabit Ethernet (GbE)
- SONET/SDH
- PCI Express
- CPRI/OBSAI wireless base stations
- Fibre Channel
- SAS/SATA
- DIMM

### Ordering Information

| Part Number    | Marking      | Shipping      | Ambient Temp. Range | Package | Lead Finish |
|----------------|--------------|---------------|---------------------|---------|-------------|
| PL904xxxUMG    | PL904<br>XXX | Tray          | -40° to +85°C       | QFN-32L | NiPdAu      |
| PL904xxxUMG TR | PL904<br>XXX | Tape and Reel | -40° to +85°C       | QFN-32L | NiPdAu      |

### Pin Configuration



32-Pin QFN (5mm x 5mm)

## Pin Description

| Pin Number  | Pin Name                   | Pin Type | Pin Level | Pin Function  |
|---|----------------------------|----------|-----------|---|
| 18, 19<br>22, 23  | OUTB, /OUTB<br>OUTA, /OUTA | O        | Various   | Clock outputs.<br>Can be programmed to one of the following logic types: <sup>(1)</sup><br>LVPECL, LVDS, HCSL, or LVCMOS. |
| 26, 27  | REFIN, /REFIN              | I        | Various   | Reference clock input.<br>Can be programmed to either differential or single-ended use.                                   |
| 20<br>16  | OE_A<br>OE_B               | I        | CMOS      | Output Enable, Outputs disable to tri-state,<br>0 = Disabled, 1 = Enabled, on-chip 75kΩ pull-up                           |
| 1, 2, 5, 8, 25  | VDD                        | PWR      |           | Core power supply.  |
| 28  | VDDI                       | PWR      |           | Input circuit power supply, +3.3V only.   |
| 24  | VDDA                       | PWR      |           | Analog circuit power supply.  |
| 21<br>17  | VDDOA<br>VDDOB             | PWR      |           | Output buffers power supply.  |
| EPAD  | VSS                        | PWR      |           | Power supply ground and thermal relief. <sup>(2)</sup>  |
| 11  | GND                        | I        |           | This pin is not power supply ground, but must be tied to VSS for proper operation.  |
| 3, 4, 6, 7, 9, 10,<br>12, 13, 14, 15,<br>29, 30, 31, 32 | DNC                        |          |           | Internally connected. Do not connect anything to these pins.  |

**Note:**

1. In case of LVCMOS, only the true output pin is enabled. The complementary output pin is disabled to a high impedance.
2. Exposed package pad is electrically active and must be connected to ground.

## Functional Description

The PL904xxx series is a very flexible, advanced programmable jitter filter design for high performance, small form-factor applications. The PL904xxx accepts a reference clock input between 12MHz and 250MHz that can be either differential or single-ended. The PL904xxx is capable of producing up to 2 differential outputs up to 850MHz. The most common configuration will be with the same input and output frequency, but this flexible design also allows frequency translation from one frequency to another frequency, as long as both frequencies are within the specified ranges for input and output.

### Jitter Attenuation

Typically, the jitter attenuation settings will be optimized for one particular input and output frequency.

The PL904xxx excels at attenuating deterministic jitter that presents itself as spurs in the phase noise plot above 1MHz.

### Output Logic Programming

Available output logic types are LVPECL, LVDS, HCSL, and LVCMOS.

Each output can be programmed individually to one of the four logic types.

All logic types are differential, except LVCMOS. For LVCMOS, only the true channel of the output pair is enabled and the complementary channel is disabled. With LVCMOS, there is also an output drive setting. There is one setting for all LVCMOS outputs, so all LVCMOS outputs will have the same drive strength.

Unused outputs are disabled to high impedance.

### Input Selection

The reference input for the device can be programmed to be either differential or single ended and requires only a small amplitude. See [Figure 1](#) and [Figure 2](#).

The single-ended signal can be LVCMOS and the differential signal can be any of the differential logic types. For the differential logic types, it is important to use the appropriate termination for the logic type.

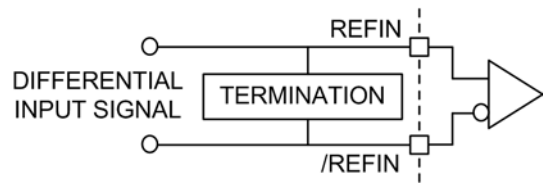


Figure 1. Differential Input Signal

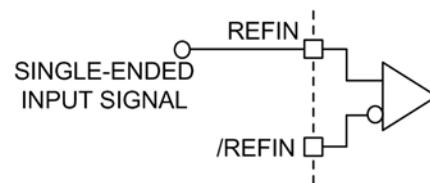


Figure 2. Single-Ended Input Signal

**Absolute Maximum Ratings<sup>(3)</sup>**

|   |                          |
|---|--------------------------|
| Supply Voltage ( $V_{DD}$ , $V_{DDI}$ , $V_{DDA}$ , $V_{DDOA/B}$ )..... | +4.6V                    |
| Input Voltage ( $V_{IN}$ ) .....  | -0.5V to $V_{DD} + 0.5V$ |
| Lead Temperature (soldering, 20s).....                                  | 260°C                    |
| Case Temperature .....  | 115°C                    |
| Storage Temperature ( $T_s$ ).....                                      | -65°C to +150°C          |

**Operating Ratings<sup>(4)</sup>**

|  |                    |
|--|--------------------|
| Supply Voltage<br>( $V_{DD}$ , $V_{DDA}$ , $V_{DDOA/B}$ , $V_{DDI}$ ).....       | +2.375V to +3.465V |
| Ambient Temperature ( $T_A$ ) .....  | -40°C to +85°C     |
| Junction Thermal Resistance <sup>(5)</sup><br>( $\theta_{JA}$ ), Still-Air ..... | 34°C/W             |

**DC Electrical Characteristics<sup>(6)</sup>**

$V_{DD}$ ,  $V_{DDA}$ ,  $V_{DDOA/B}$ ,  $V_{DDI} = 2.375V \sim 3.465V$ ;  $T_A = -40^\circ C$  to  $+85^\circ C$ .

| Symbol                                | Parameter                                | Condition  | Min.  | Typ. | Max.  | Units |
|---------------------------------------|--|--|-------|------|-------|-------|
| $V_{DD}$<br>$V_{DDA}$<br>$V_{DDOA/B}$ | Power supply voltage                     |  | 2.375 |      | 3.465 | V     |
| $V_{DDI}$                             | Power supply voltage                     |  | 3.135 |      | 3.465 | V     |
| $I_{DD}$                              | Total supply current, $V_{DD} + V_{DDO}$ | 2 x LVPECL, 156.25MHz<br>Outputs open                              |       |      | 220   | mA    |
|                                       |  | 2 x HCSL (PCIe), 100MHz<br>Outputs terminated with 50Ω to $V_{SS}$ |       |      | 230   | mA    |
|                                       |  | 2 x LVCMOS, 125MHz<br>Outputs open                                 |       |      | 210   | mA    |

**REFIN DC Electrical Characteristics<sup>(6)</sup>**

$V_{DDI} = 3.135V \sim 3.465V$ ;  $T_A = -40^\circ C$  to  $+85^\circ C$ .

| Symbol      | Parameter                 | Condition  | Min. | Typ. | Max.            | Units    |
|-------------|---------------------------|--|------|------|-----------------|----------|
| $V_{CMR}$   | Input common mode voltage |  | 0.3  |      | $V_{DDI} - 0.3$ | V        |
| $V_{SWING}$ | Input voltage swing       | Peak to peak. Each side of the differential input. | 0.2  |      | $V_{DDI}$       | $V_{PP}$ |

**Notes:**

- Exceeding the absolute maximum ratings may damage the device.
- The device is not guaranteed to function outside its operating ratings.
- Package thermal resistance assumes the exposed pad is soldered (or equivalent) to the device's most negative potential on the PCB.
- The circuit is designed to meet the AC and DC specifications shown in the Electrical Characteristics tables after thermal equilibrium has been established.

## LVDS Output DC Electrical Characteristics<sup>(6)</sup>

$V_{DDO/A/B} = 2.375V \sim 3.465V$ ,  $T_A = -40^{\circ}C$  to  $+85^{\circ}C$ ,  $R_L = 100\Omega$  across Q and /Q.

| Symbol   | Parameter                   | Condition | Min.  | Typ.  | Max.  | Units |
|----------|-----------------------------|-----------|-------|-------|-------|-------|
| $V_{OD}$ | Differential output voltage |           | 245   | 350   | 454   | mV    |
| $V_{CM}$ | Common mode voltage         |           | 1.125 | 1.2   | 1.375 | V     |
| $V_{OH}$ | Output high voltage         |           | 1.248 | 1.375 | 1.602 | V     |
| $V_{OL}$ | Output low voltage          |           | 0.898 | 1.025 | 1.252 | V     |

## HCSL Output DC Electrical Characteristics<sup>(6)</sup>

$V_{DDO/A/B} = 2.375V \sim 3.465V$ ,  $T_A = -40^{\circ}C$  to  $+85^{\circ}C$ ,  $R_L = 50\Omega$  to  $V_{SS}$

| Symbol      | Parameter              | Condition | Min. | Typ. | Max. | Units |
|-------------|------------------------|-----------|------|------|------|-------|
| $V_{OH}$    | Output high voltage    |           | 660  | 700  | 850  | mV    |
| $V_{OL}$    | Output low voltage     |           | -150 | 0    | 27   | mV    |
| $V_{CROSS}$ | Crossing point voltage |           |      | 350  |      | mV    |

## LVPECL Output DC Electrical Characteristics<sup>(6)</sup>

$V_{DDO/A/B} = 2.375V \sim 3.465V$ ,  $T_A = -40^{\circ}C$  to  $+85^{\circ}C$ ,  $R_L = 50\Omega$  to  $V_{DD} - 2V$

| Symbol      | Parameter            | Condition | Min.             | Typ.             | Max.             | Units |
|-------------|----------------------|-----------|------------------|------------------|------------------|-------|
| $V_{OH}$    | Output high voltage  |           | $V_{DDO} - 1.35$ | $V_{DDO} - 1.01$ | $V_{DDO} - 0.80$ | V     |
| $V_{OL}$    | Output low voltage   |           | $V_{DDO} - 2.00$ | $V_{DDO} - 1.78$ | $V_{DDO} - 1.60$ | V     |
| $V_{SWING}$ | Output voltage swing |           | 0.65             | 0.77             | 0.95             | V     |

## LVC MOS Output DC Electrical Characteristics<sup>(6)</sup>

$V_{DDO/A/B} = 2.375V \sim 3.465V$ ,  $T_A = -40^{\circ}C$  to  $+85^{\circ}C$ ,  $R_L = 50\Omega$  to  $V_{DD}/2$

| Symbol   | Parameter           | Condition | Min.           | Typ. | Max. | Units |
|----------|---------------------|-----------|----------------|------|------|-------|
| $V_{OH}$ | Output high voltage |           | $V_{DD} - 0.8$ |      |      | V     |
| $V_{OL}$ | Output low voltage  |           |                |      | 0.5  | V     |

## OE (LVC MOS) Input DC Electrical Characteristics<sup>(6)</sup>

$V_{DD}$ ,  $V_{DDA}$ ,  $V_{DDO/A/B} = 2.375V \sim 3.465V$ ;  $V_{DDI} = 3.135V \sim 3.465V$ ,  $T_A = -40^{\circ}C$  to  $+85^{\circ}C$

| Symbol   | Parameter          | Condition                         | Min.           | Typ. | Max.                | Units   |
|----------|--------------------|-----------------------------------|----------------|------|---------------------|---------|
| $V_{IH}$ | Input high voltage |                                   | $V_{DD} - 0.7$ |      | $V_{DD} + 0.3$      | V       |
| $V_{IL}$ | Input low voltage  |                                   | $V_{SS} - 0.3$ |      | $0.3 \times V_{DD}$ | V       |
| $I_{IH}$ | Input high current | $V_{DD} = V_{IN} = 3.465V$        |                |      | 5                   | $\mu A$ |
| $I_{IL}$ | Input low current  | $V_{DD} = 3.465V$ , $V_{IN} = 0V$ | -150           |      |                     | $\mu A$ |

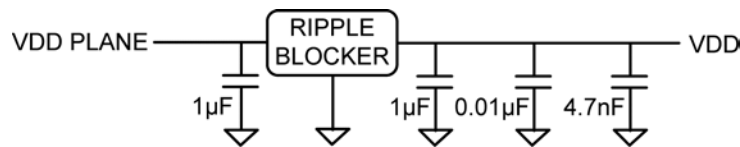
## AC Electrical Characteristics

$V_{DD}, V_{DDA}, V_{DDOA/B}, V_{DDI} = 2.375V \sim 3.465V; T_A = -40^{\circ}C \text{ to } +85^{\circ}C.$

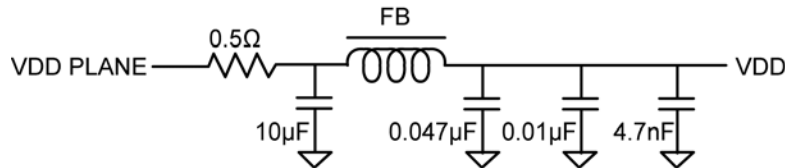
| Symbol     | Parameter   | Condition                      | Min. | Typ. | Max. | Units |
|------------|---|--------------------------------|------|------|------|-------|
| $F_{IN}$   | Input frequency                                       |                                | 12   |      | 250  | MHz   |
| $F_{OUT}$  | Output frequency                                      | LVPECL, LVDS, HCSL             | 12   |      | 850  | MHz   |
|            |   | LVC MOS                        | 12   |      | 250  | MHz   |
| $T_R/T_F$  | Output rise/fall time<br>See <a href="#">Figure 4</a> | LVPECL output                  | 85   | 135  | 350  | ps    |
|            |   | LVDS output                    | 85   | 140  | 300  | ps    |
|            |   | HCSL output                    | 175  | 340  | 700  | ps    |
|            |   | LVC MOS output (default drive) | 100  | 200  | 400  | ps    |
| ODC        | Output duty cycle<br>See <a href="#">Figure 3</a>     | All output frequencies         | 45   | 50   | 55   | %     |
|            |   | <350MHz output frequencies     | 48   | 50   | 52   | %     |
| $T_{LOCK}$ | PLL lock time   |                                |      | 5    | 20   | ms    |

## Power Supply Filtering Recommendations

Preferred filter, using Micrel's MIC94300 or MIC94310 Ripple Blocker™:



Alternative, traditional filter, using a ferrite bead:



VDDO and VDD pins can be connected directly to the VDD power plane. For VDDA and VDDI it is recommended to use a power supply filter as described above.

## Application Information

### Power Supply Decoupling

Place the smallest value decoupling capacitor (4.7nF above) between the VDD and VSS pins, as close as possible to those pins and on the same side of the PCB as the IC. The shorter the physical path from VDD to the capacitor and back from the capacitor to VSS, the more effective the decoupling. Use one 4.7nF capacitor for each VDD pin on the PL904xxx.

The impedance value of the ferrite bead (FB) needs to be between 240Ω and 600Ω with a saturation current  $\geq 150\text{mA}$ .

VDDO pins connect directly to the VDD plane. All VDD pins on the PL904xxx connect to VDD after the power supply filter.

A Ripple Blocker has advantages over using a ferrite bead. A Ripple Blocker filters much lower frequencies than a ferrite bead, at least two decades lower. Most ferrite beads cause peaking in the noise filter frequency response, so some noise frequencies are actually made worse. The Ripple Blocker is designed to not have any noise peaking.

### Output Traces

Design the traces for the output signals according to the output logic requirements. If LVCMOS is unterminated, add a 30Ω resistor in series with the output, as close as possible to the output pin, and start a 50Ω trace on the other side of the resistor.

For differential traces, you can either use a differential design or two separate 50Ω traces. For EMI reasons, it is better to use a differential design.

LVDS can be AC-coupled or DC-coupled to its termination.



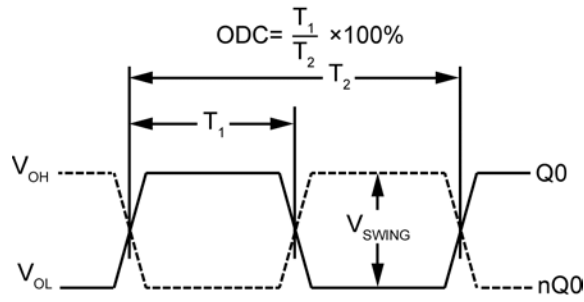


Figure 3. Duty Cycle Timing

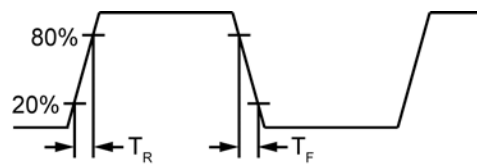
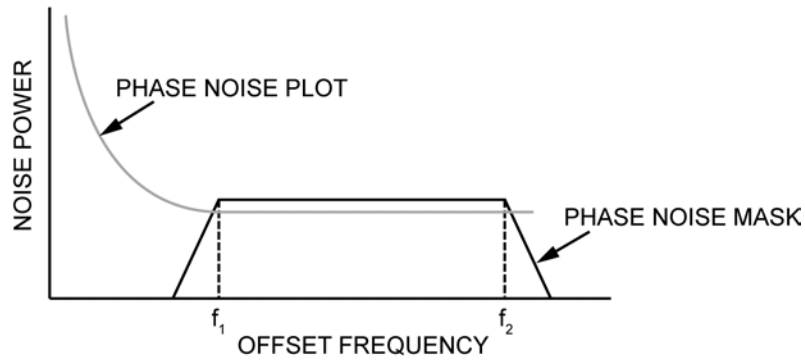


Figure 4. All Outputs Rise/Fall Time

RMS PHASE NOISE/JITTER



$$RMS\ JITTER = \sqrt{\text{AREA UNDER THE MASKED PHASE NOISE PLOT}}$$

Figure 5. RMS Phase Noise Jitter

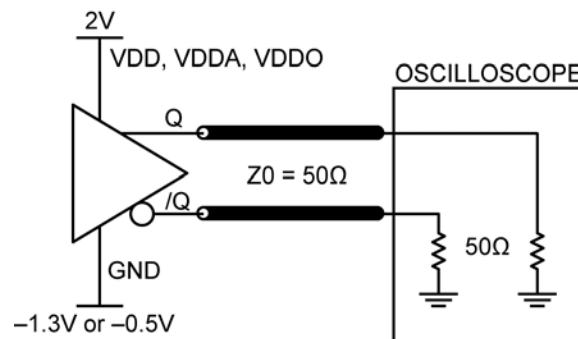


Figure 6. LVPECL Output Load and Test Circuit

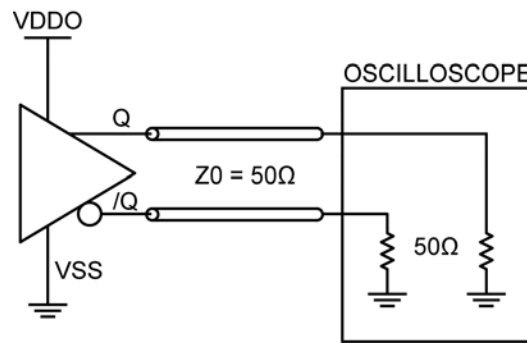


Figure 7. HCSL Output Load and Test Circuit

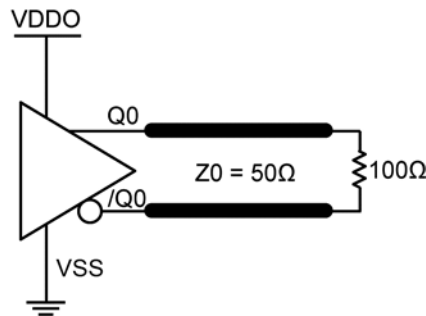


Figure 8. LVDS Output Load and Test Circuit

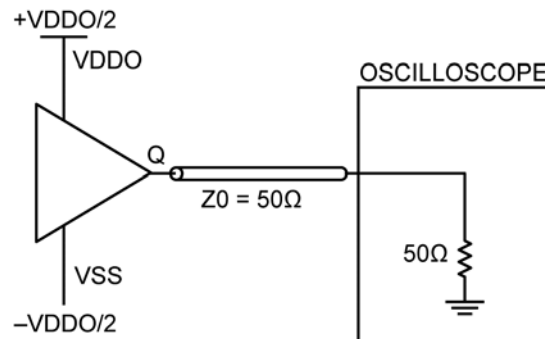
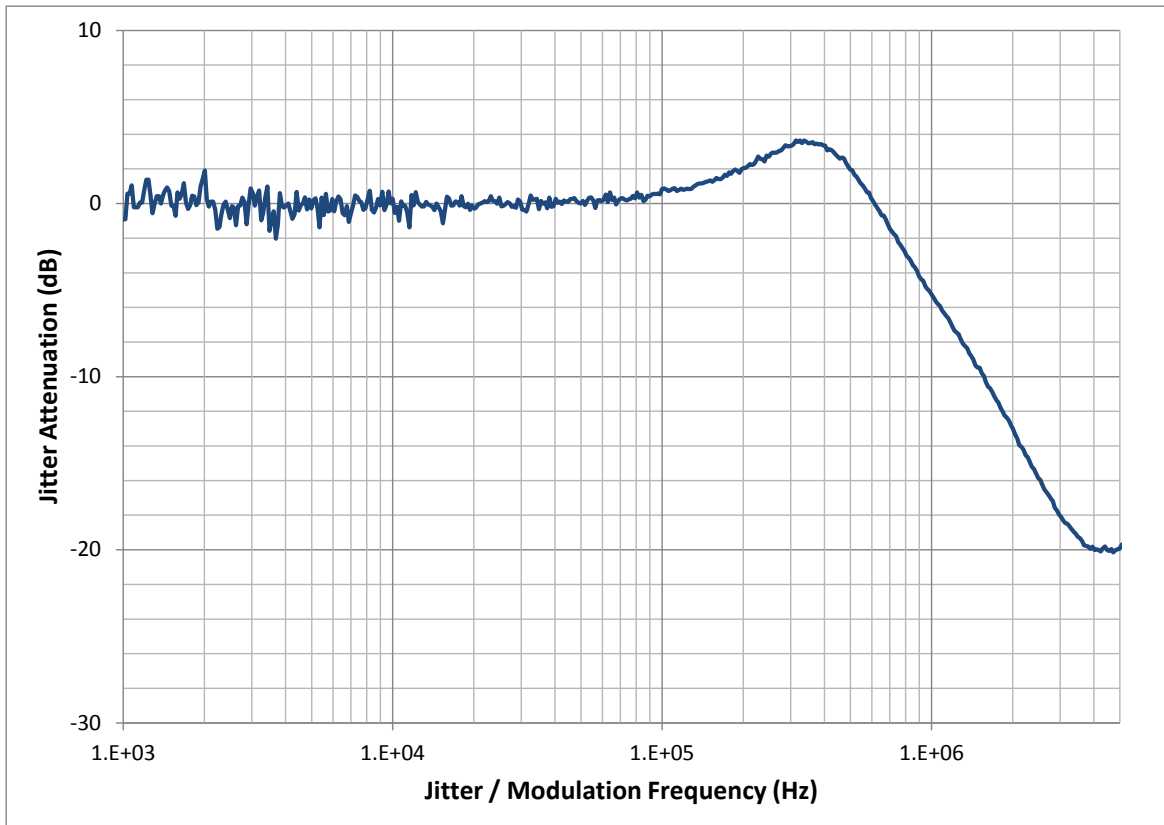


Figure 9. LVC MOS Output Load and Test Circuit

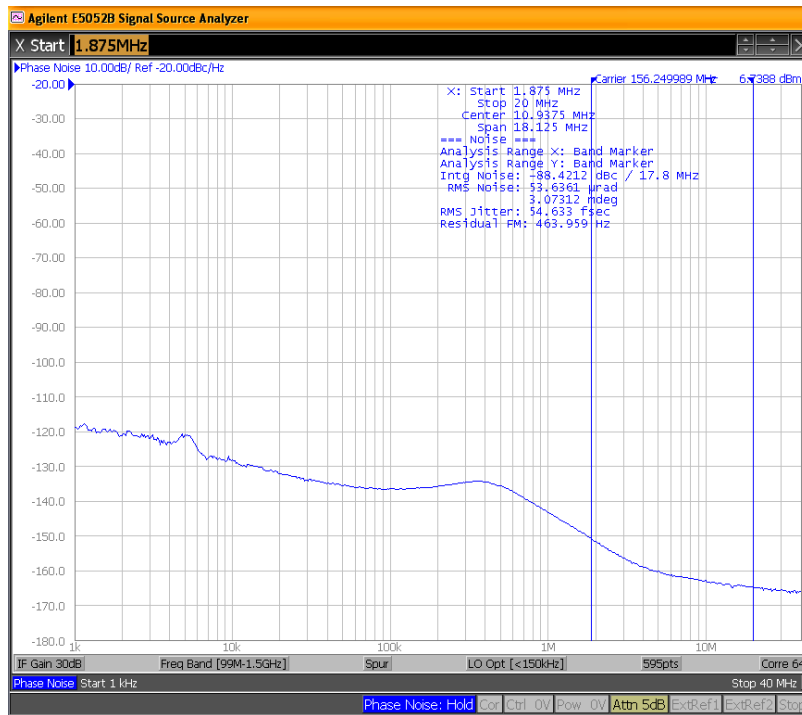
## Jitter Attenuation Performance

The jitter attenuating frequency response was measured at 156.25MHz.

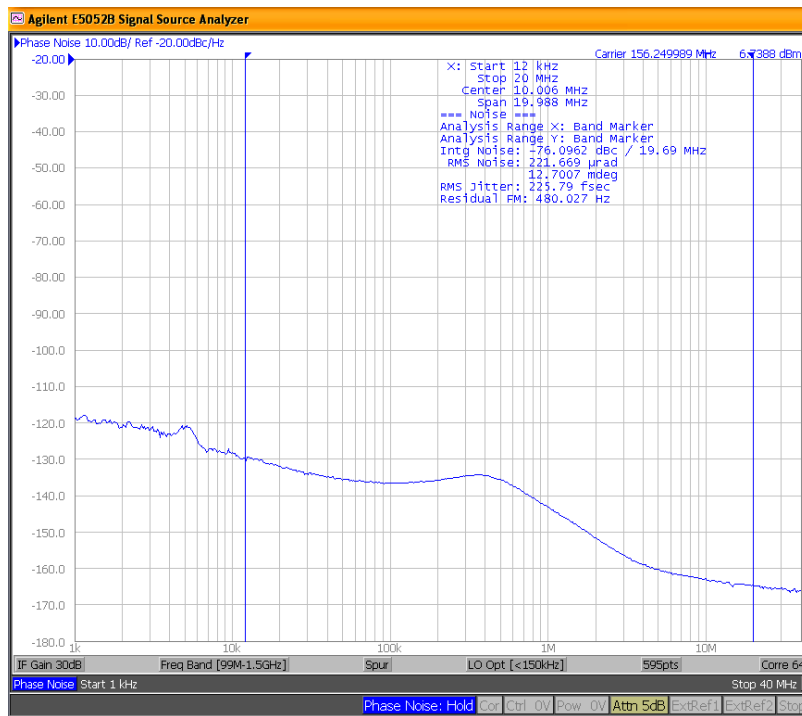


The jitter attenuation works like a low-pass filter for frequency modulated signals or noise. The bandwidth for this low-pass filter is 500kHz with a 12dB/octave slope above 500kHz. At about 5MHz the noise floor of this measurement is reached but in reality, the attenuation continues with the 12dB/octave slope.

Phase noise performance with a clean input clock.

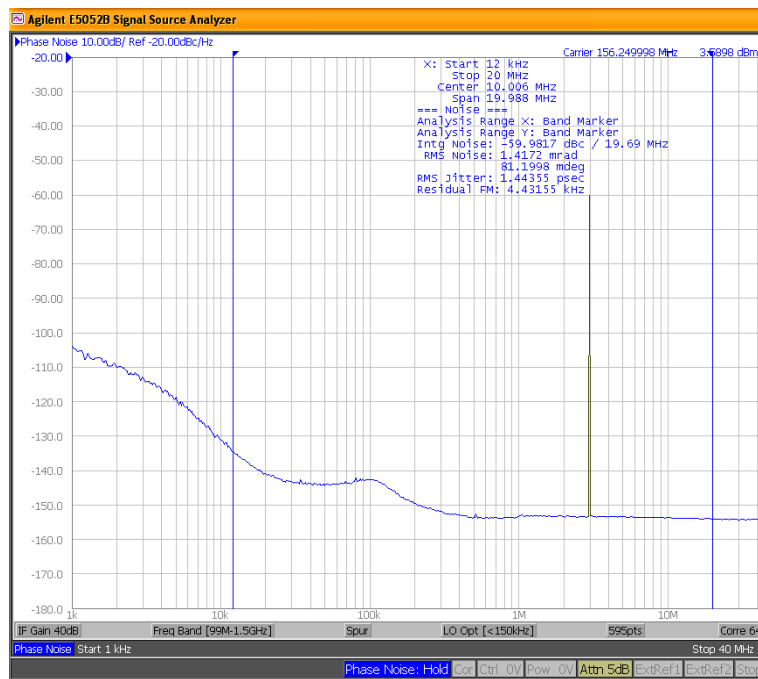


156.25MHz with 55fs<sub>RMS</sub> of phase jitter for 1.875MHz to 20MHz integration range



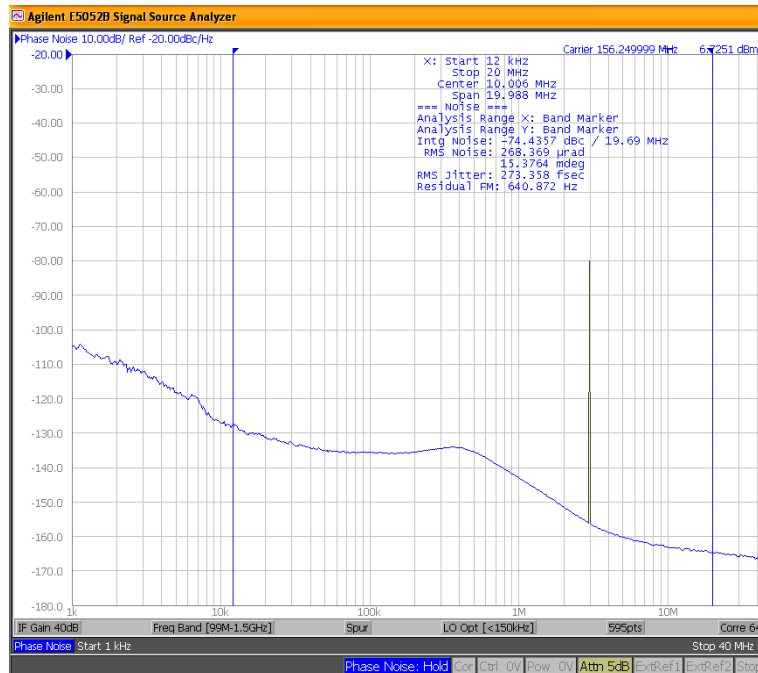
156.25MHz with 226fs<sub>RMS</sub> of phase jitter for 12kHz to 20MHz integration range

Example 156.25MHz input test clock with bad phase jitter cause by a 3MHz spur.



156.25MHz with 1.4ps<sub>RMS</sub> of phase jitter for 12kHz to 20MHz integration range

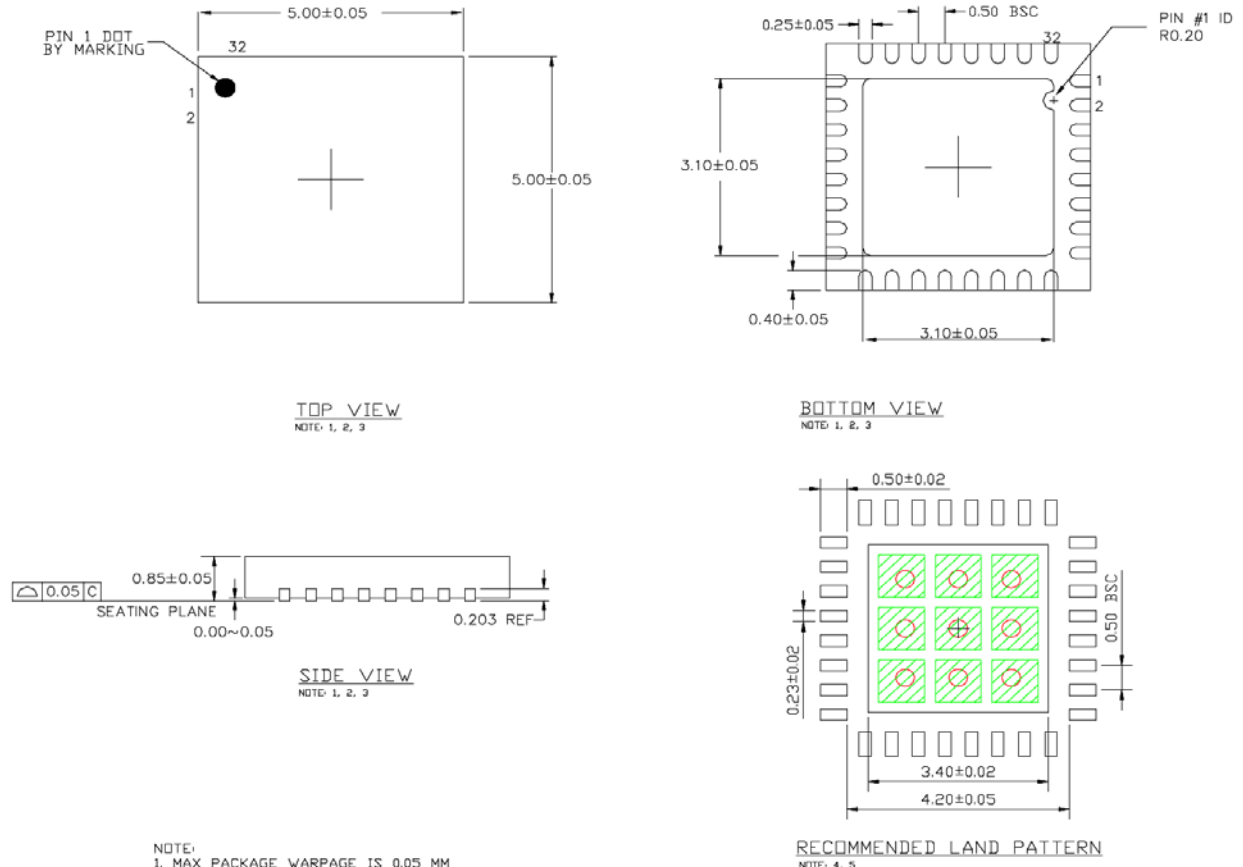
Output clock from PL904xxx.



156.25MHz with 273fs<sub>RMS</sub> of phase jitter for 12kHz to 20MHz integration range

The 3MHz spur is attenuated by 20dB, resulting in a phase jitter reduction from 1.4ps to 0.27ps.

# Package Information and Recommended Landing Pattern<sup>(7)</sup>



- NOTE:
1. MAX PACKAGE WARPAGE IS 0.05 MM
  2. MAX ALLOWABLE BURR IS 0.076MM IN ALL DIRECTIONS
  3. PIN #1 IS ON TOP WILL BE LASER MARKED
  4. RED CIRCLE IN LAND PATTERN INDICATE THERMAL VIA. SIZE SHOULD BE 0.30-0.3M IN DIAMETER AND SHOULD BE CONNECTED TO GND FOR MAX THERMAL PERFORMANCE
  5. GREEN RECTANGLES (SHADED AREA) INDICATE SOLDER STENCIL OPENING ON EXPOSED PAD AREA. SIZE SHOULD BE 0.87x0.87 MM IN SIZE, 1.07 MM PITCH.

## 32-Pin QFN

**Note:**

7. Package information is correct as of the publication date. For updates and most current information, go to [www.micrel.com](http://www.micrel.com).

---

**MICREL, INC. 2180 FORTUNE DRIVE SAN JOSE, CA 95131 USA**  
TEL +1 (408) 944-0800 FAX +1 (408) 474-1000 WEB <http://www.micrel.com>

Micrel, Inc. is a leading global manufacturer of IC solutions for the worldwide high performance linear and power, LAN, and timing & communications markets. The Company's products include advanced mixed-signal, analog & power semiconductors; high-performance communication, clock management, MEMs-based clock oscillators & crystal-less clock generators, Ethernet switches, and physical layer transceiver ICs. Company customers include leading manufacturers of enterprise, consumer, industrial, mobile, telecommunications, automotive, and computer products. Corporation headquarters and state-of-the-art wafer fabrication facilities are located in San Jose, CA, with regional sales and support offices and advanced technology design centers situated throughout the Americas, Europe, and Asia. Additionally, the Company maintains an extensive network of distributors and reps worldwide.

Micrel makes no representations or warranties with respect to the accuracy or completeness of the information furnished in this datasheet. This information is not intended as a warranty and Micrel does not assume responsibility for its use. Micrel reserves the right to change circuitry, specifications and descriptions at any time without notice. No license, whether express, implied, arising by estoppel or otherwise, to any intellectual property rights is granted by this document. Except as provided in Micrel's terms and conditions of sale for such products, Micrel assumes no liability whatsoever, and Micrel disclaims any express or implied warranty relating to the sale and/or use of Micrel products including liability or warranties relating to fitness for a particular purpose, merchantability, or infringement of any patent, copyright, or other intellectual property right.

Micrel Products are not designed or authorized for use as components in life support appliances, devices or systems where malfunction of a product can reasonably be expected to result in personal injury. Life support devices or systems are devices or systems that (a) are intended for surgical implant into the body or (b) support or sustain life, and whose failure to perform can be reasonably expected to result in a significant injury to the user. A Purchaser's use or sale of Micrel Products for use in life support appliances, devices or systems is a Purchaser's own risk and Purchaser agrees to fully indemnify Micrel for any damages resulting from such use or sale.

© 2015 Micrel, Incorporated.